WELCOME TO 2016 HOT CHIPS

Stefan Rusu
HC28 General Chair

2016 Hot Chips #28

- Largest attendance in the last 15 years!
  - Thank you all for making HC28 successful
- Strong technical program
  - Many new architectural disclosures
- Broad sponsor support
  - Please visit the sponsors demo tables

Thanks to Our Sponsors!

Platinum Sponsors

Gold Sponsors

Silver Sponsors

Attendee Gifts

128GB USB memory stick!
Use it every day

HC28 tote bag
Pick yours at registration

HOT CHIPS NEW

A Better Attendee Experience

- Projection in full HD (16:9 format) on larger screen
- Full HD videos of all presentations after conference
- Hot Chips presentations on IEEE Explore back to 2005, also available at www.hotchips.org/archives/
- Internet access throughout Flint Center
- All meals, snacks, coffee are included
- Flat registration fees in spite of rising costs

Conference Schedule

Monday ➡

9:30 – 9:45am	Introductory Remarks	
9:45 – 11:15am	Session 1	GPUs & HPCs
11:15 – 11:45am	Break	Poster presentations
11:45 – 12:45pm	Session 2	Mobile
12:45 – 2:15pm	Lunch	
2:15 – 3:00pm	Keynote 1	Mixed Reality Nick Baker, **Microsoft**
3:00 – 4:00pm	Session 3	Low Power SoC
4:00 – 4:30pm	Break	Poster presentations
4:30 – 6:00pm	Session 4	Vision & Imaging
6:00 – 7:30 pm	Reception	

Tuesday ➡

8:30 – 10:00am	Session 5	Interconnects
10:00 -- 10:30am	Break	Poster presentations resentations
10:30 – 12:00pm	Session 6	Emerging Embedded Embedded
12:00 – 1:15pm	Lunch	
1:15 – 2:15pm	Keynote 2	Self-Driving Cars Daniel Rosenband, **Google**
2:15 – 3:15pm	Session 7	Multicore Research
3:15 -- 3:45pm	Break	Poster presentations
3:45 – 5:15pm	Session 8	Dealing with Big Data
5:15 – 5:45pm	Break	Poster presentations
5:45 – 7:15pm	Session 9	Processors
7:15 – 7:30pm	Closing Remarks	

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Parking

- You must display this parking pass in your dashboard
- Get one from registration
- Park in Lots A or B at the East end of campus ONLY!
- Parking in Staff Lots or 30 minute only spots will earn you a parking ticket

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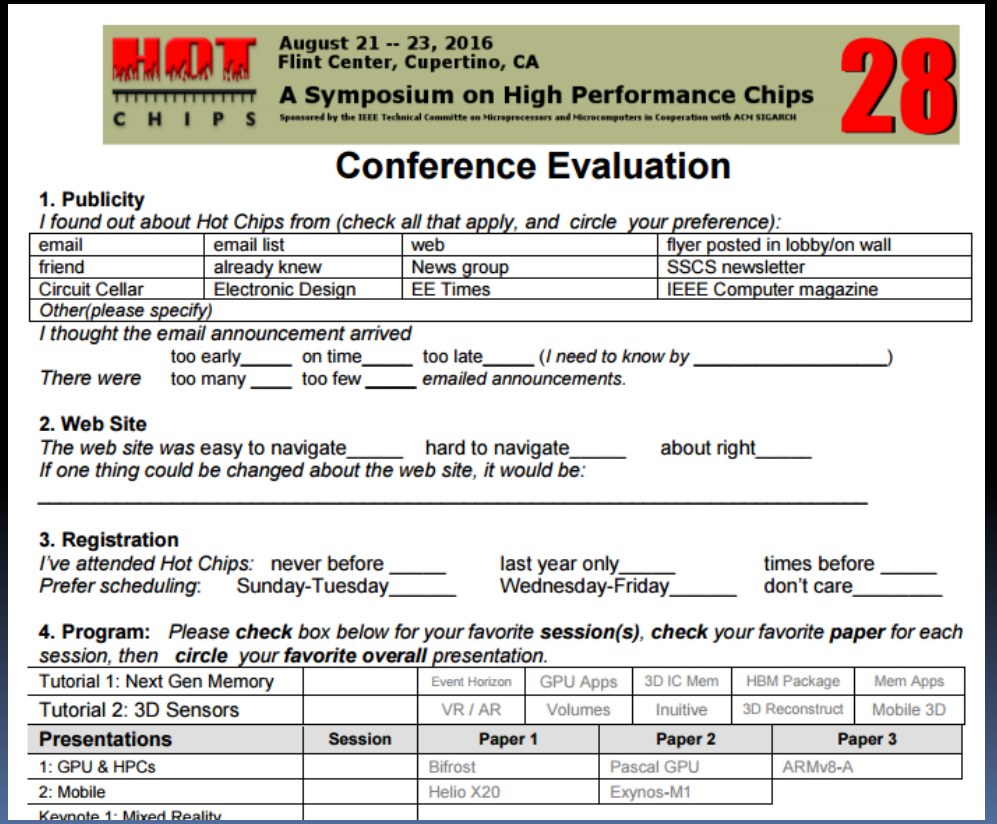
We Need Your Feedback!

- Please let us know how we can improve the conference
- Fill up an evaluation form and drop it off at the registration desk



HOT CHIPS 28

August 21 -- 23, 2016
Flint Center, Cupertino, CA

A Symposium on High Performance Chips

Sponsored by the IEEE Technical Committe on Microprocessors and Microcomputers in Cooperation with ACM SIGARCH

Conference Evaluation

1. Publicity

I found out about Hot Chips from (check all that apply, and circle your preference):

email	email list	web	flyer posted in lobby/on wall
friend	already knew	News group	SSCS newsletter
Circuit Cellar	Electronic Design	EE Times	IEEE Computer magazine
Other(please specify)			

I thought the email announcement arrived
too early_____ on time_____ too late_____ (*I need to know by* _____)
There were too many ____ too few _____ *emailed announcements.*

2. Web Site

The web site was easy to navigate_____ hard to navigate_____ about right_____
If one thing could be changed about the web site, it would be:
_____

3. Registration

I've attended Hot Chips: never before _____ last year only_____ times before _____
Prefer scheduling: Sunday-Tuesday_____ Wednesday-Friday_____ don't care_____

4. Program: *Please **check** box below for your favorite **session(s)**, **check** your favorite **paper** for each session, then **circle** your **favorite overall** presentation.*

Tutorial 1: Next Gen Memory		Event Horizon	GPU Apps	3D IC Mem	HBM Package	Mem Apps
Tutorial 2: 3D Sensors		VR / AR	Volumes	Inuitive	3D Reconstruct	Mobile 3D

Presentations	Session	Paper 1	Paper 2	Paper 3
1: GPU & HPCs		Bifrost	Pascal GPU	ARMv8-A
2: Mobile		Helio X20	Exynos-M1	
Keynote 1: Mixed Reality				

HOT NEW CHIPS

Program Committee

Co-Chairs	Bryan Chin	Onramp Bioinformatics
	Subhasish Mitra	Stanford University
Members	Forest Baskett	NEA
	Alan Smith	UC Berkeley
	Pradeep Dubey	Intel
	Ralph Wittig	Xilinx
	Yoshio Masubuchi	Toshiba
	Bill Dally	Nvidia
	Chris Rowen	Cadence
	David Lau	Imagination
	David Brash	ARM
	Mike Taylor	UC San Diego
	John Sell	Microsoft
	Sameer Nanavati	Qualcomm
	Larry Yang	Google

Meet us during the breaks - we want to hear your feedback!

Hot Chips 28 Program

- Geo Diversity (***not just Silicon Valley)*** **38 %** papers/posters ***outside*** NA
- Topic Diversity (not just microprocessors)
  - Microprocessors (IBM, AMD, Samsung, Mediatek, Intel, Princeton, UC Davis)
  - Architecture - new vector architecture (ARM and Fujitsu)
  - GPU and HPC Accelerators (ARM, NVIDIA)
  - Machine Vision chips (Deephi and Tsinghua, CEVA, Cadence)
  - Interconnects (TSMC, InPhi and Microsoft)
  - New chips for embedded (Sentons, InVisage, Levant (ClearMotion))
  - Machine learning and big data Accelerators (Movidius, Oracle, Baidu)
  - Keynotes: Mixed Reality (Microsoft) & Self Driving Cars (Google)

Reminder - see our 14 posters and sponsors during breaks and lunches